



PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

November 24, 2010

Applicants: Toshihiro TAI et al
For: PLATED RESIN MOLDED ARTICLES
Serial No.: 10/586 378 Group: 1787
Confirmation No.: 2951
Filed: July 14, 2006 Examiner: Kruer
International Application No.: PCT/JP2005/002827
International Filing Date: February 16, 2005
Atty. Docket No.: 3400.P1434US

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE

Sir:

In response to the Office Action dated October 1, 2010,
please amend the above-identified application as follows:

(Please see following pages.)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service with
sufficient postage as first class mail in an envelope
addressed to: Commissioner for Patents, P.O. Box 1450,
Alexandria, VA 22313-1450, on November 24, 2010.


Terrance F. Chapman